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# 91A  
4-4-01  
R. Diab

501.32049R00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: KAJIHARA, et al.

Serial No.: 09/328,910

Filed: June 9, 1999



For: LEADFRAME, SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE  
USING THE SAME, AND METHOD OF AND PROCESS FOR  
FABRICATING THE TWO

Art Unit: 2811

Examiner: unassigned

PRELIMINARY AMENDMENT

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

October 13, 2000

Sir:

The following is respectfully submitted in connection with the above-identified  
application.

IN THE CLAIMS:

Please add the following new claims:

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OCT 30 2000  
TC 2800 MAIL ROOM

-- 63. A semiconductor device comprising:

(1) a semiconductor chip having a main surface and a rear surface opposite to  
said main surface, said semiconductor chip having a plurality of semiconductor elements  
and bonding pads formed on said main surface;

(2) a lead frame including:

10/23/2000 MMARMOL 00000001 09328910

01 FC:102  
02 FC:103

160.00 OP  
180.00 OP

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